



JFW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Wilkins

Title : Die-First Multi-Chip Modules And Methods Of Manufacture

Application No. : 10/724,981

Filed : November 30, 2003

Attorney Docket No. : 783403605015

I hereby certify that this correspondence
is being deposited today with the United
States Postal Service as first class mail in
an envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA
22313-1450

on September 21, 2006By: Kathie G. Cochran**STATUS INQUIRY**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The above-referenced application was filed in the United States on November 30, 2003, and we have not yet received an Office Action or Notice of Allowance for the same. Please advise the undersigned when we should expect to receive an action or notice.

Respectfully submitted,

David B. Cochran
Registration No. 39,142
Jones Day
North Point
901 Lakeside Avenue
Cleveland, Ohio 44114
(216) 586-7029

Date: 9/21/06